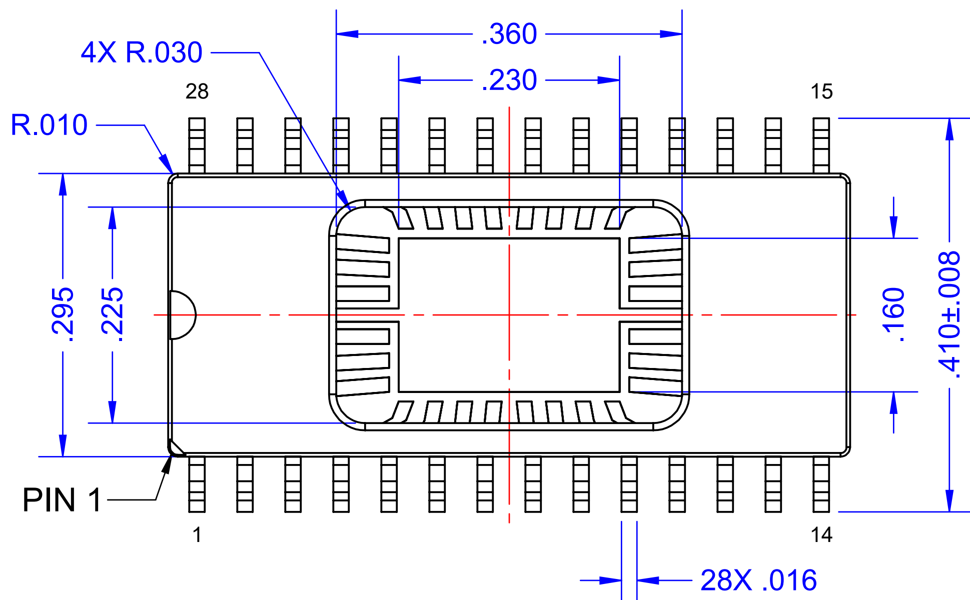
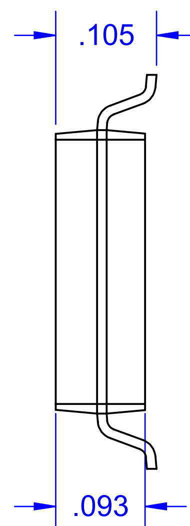
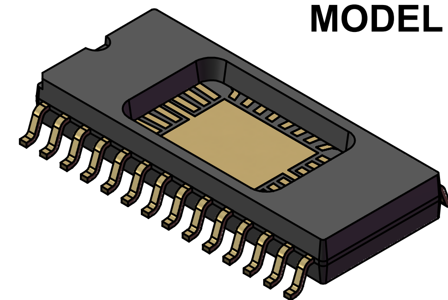
TOP VIEW

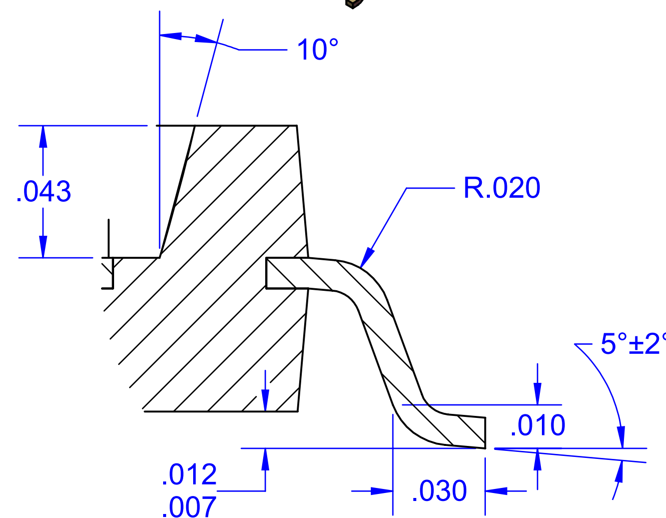


END VIEW



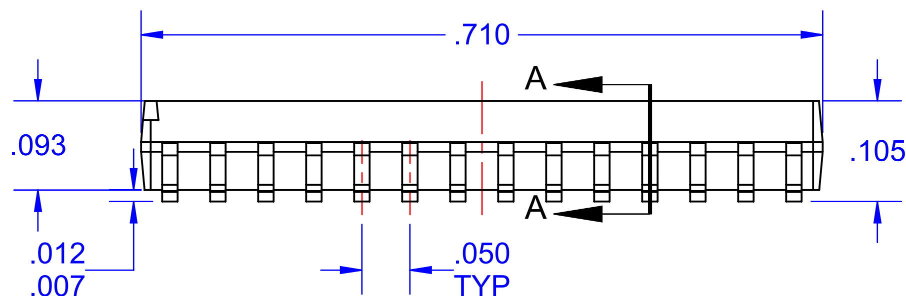
MODEL



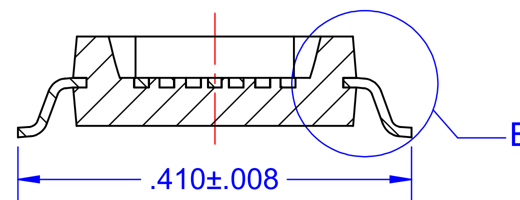


DETAIL B
SCALE 16 : 1

SIDE VIEW

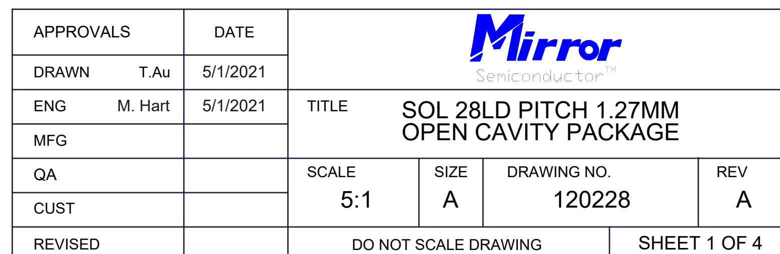


SECTION A-A



Notes: (Unless Otherwise Specified).

1) DIMENSIONS: INCHES [MM].
2) PACKAGE CONFORMS TO JEDEC MS-013.
3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
5) PLATING: NICKEL 100~300 MICROINCHES (2.5~7.6μm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.



APPROVALS		DATE	Mirror Semiconductor™			
DRAWN	T.Au	5/1/2021				
ENG	M. Hart	5/1/2021	TITLE SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE			
MFG						
QA			SCALE 5:1	SIZE A	DRAWING NO. 120228	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 4	

BOND DIAGRAM

28 27 26 25 24 23 22 21 20 19 18 17 16 15

22 21

28 15

1 14

7 8

1 2 3 4 5 6 7 8 9 10 11 12 13 14

TITLE	SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 10:1	SIZE A	DRAWING NO. 120228	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 4	

MODEL

BOTTOM

1

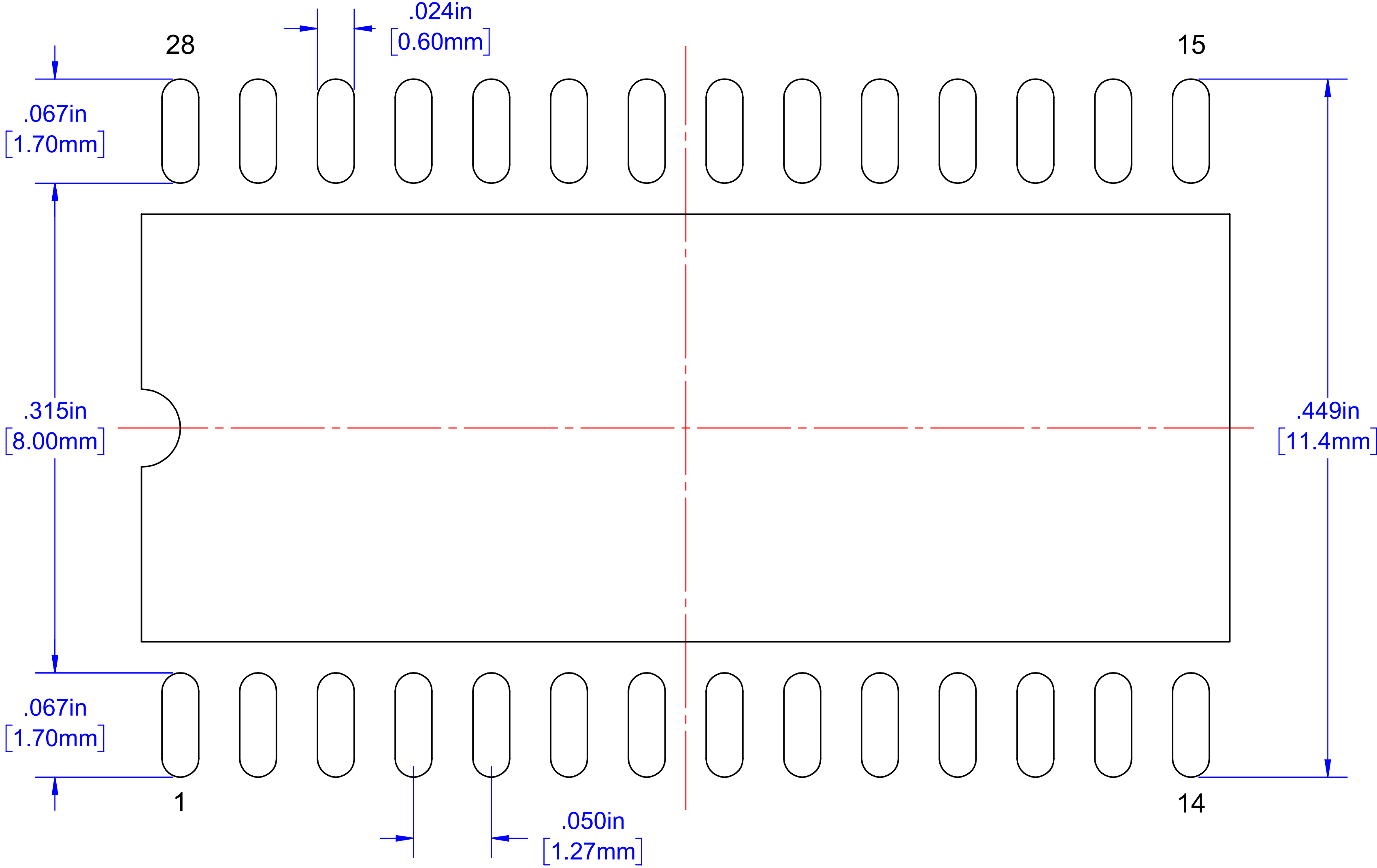
15

TOP

14

TITLE	SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 8:1	SIZE A	DRAWING NO. 120228	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

SUGGESTED PCB LAND PATTERN



Mirror Semiconductor™

TITLE	SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE	SIZE	DRAWING NO.	REV
10:1	A	120228	A

DO NOT SCALE DRAWING